

first solid state material pocket; and in which:

the solid state material layer fills the gap between the two material pockets while contacts and metallurgically perfectly bonds uniformly with a second specified portion of the second solid state material pocket; and

the solid state material layer is mechanically perfect and is no more than 3 to 40 Angstroms thick.

95. A mass-produced solid state device comprising:

a solid state material substrate;

a left and a right adjacent solid state material pockets laterally separated by a gap and positioned on a common top surface of the substrate;

a curved solid state material layer which: a) has a radius of curvature of no more than 1.0 micron; and b) is positioned on the top surface of the substrate to bridge the gap between the two solid state material pocket; and

at least a portion of the solid state material layer being metallurgically continuously bonded to at least a selected area of the top surface of the substrate with a mechanically perfect bonding interfacial region to avoid imperfectly bonded material layer leading to poor device yield, performance, reproducibility, reliability, and life.

#### REMARKS

Applicant elects the Group II claims 25-47 and 58-60, drawn to Semiconductor Device, classified in class 257, subclass 509. Claims 1-24, 48-57, and 61-65 are removed from this case without prejudice. An early action on the merits is respectfully requested

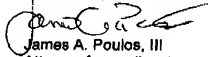
Any fee not covered by the attached check necessary to effect entry of this amendment should be charged to the undersign's deposit account 50-1770.

In view of the amendments and remarks above, Applicants submit that this

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application is in condition for allowance and request reconsideration and favorable action thereon.

Respectfully submitted,

  
James A. Poulos, III  
Attorney for applicant  
Reg. No. 31,714

Atty. Docket No. II,

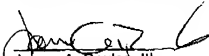
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Enclosures: marked up pages  
clean pages  
Abstract of the Disclosure  
Drawing changes

The undersigned certifies that this amendment was filed on by facsimile and transmitted to the USPTO to 703 872-9318 on August 6, 2002

  
James A. Poulos, III

Date: August 6, 2002